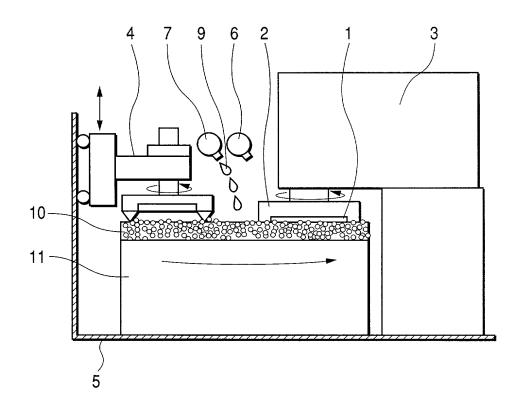
FIG. 1



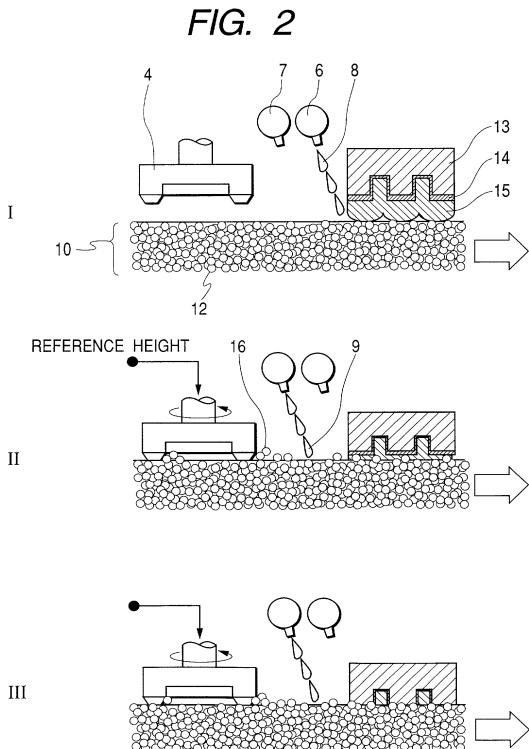


FIG. 3 1.2 1.0 Cu RELATIVE POLISHING REMOVAL RATE 8.0 BARRIER POLISHING Cu HIGH SPEED POLISHING 0.6 0.4 TaN SiO₂ 0.2 0.0 10 0 20

30

FIG. 4

OXIDIZING AGENT CONCENTRATION (%)

40

50

60

70

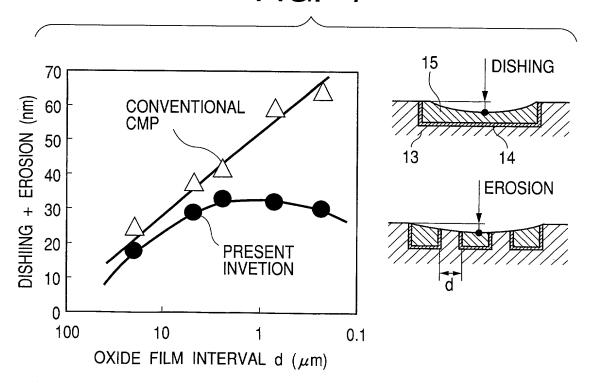


FIG. 5

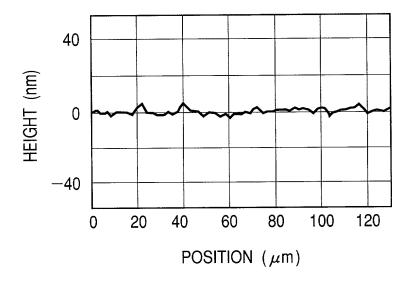
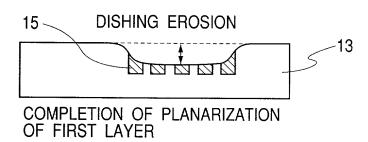
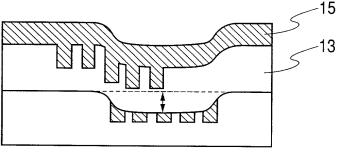
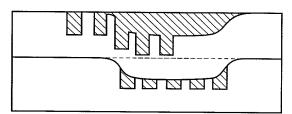


FIG. 6

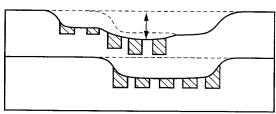




BEFORE PLANARIZING SECOND LAYER



DURING PLANARIZATION OF SECOND LAYER



COMPLETION OF PLANARIZATION OF SECOND LAYER

FIG. 7

